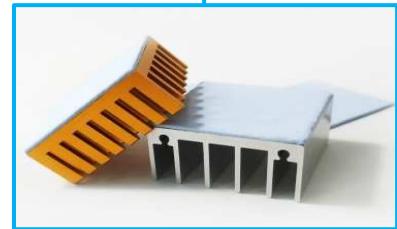


Termal Pad

Our Thermal Foam also called Gap Pad or Gap Filler are silicone-based thermo-conductive materials that solve the problems of heat dissipation. The TGF_062_AB is a mattress specially developed for applications where a high level of cooling need is required with very good compression. Indeed, this is an excellent thermal conductor of 6.2 W/mK, with good thermal resistance thus facilitating the transfer of heat and which also has excellent electrical insulation. Below 1mm, the mattress is very flexible, it is difficult to use in pick-in-place for robotic production, in this case, an adjustment of its hardness shall be made before use.

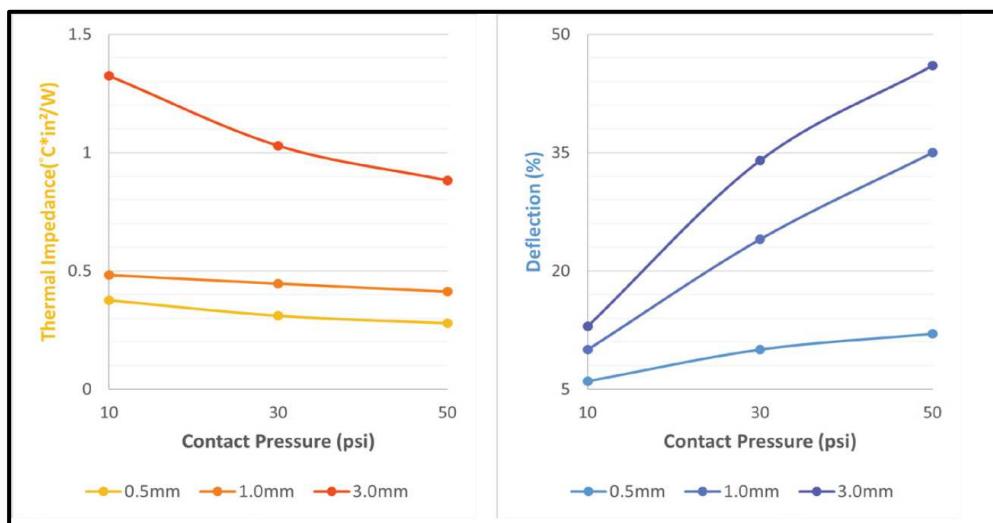


Application areas: Electronic components - Electric vehicles, 5G, Automatic driving system, Mobile phone, AIOT, HPC (High Performance Computing), Server, IC, CPU, MOS, Motherboard, Power supply, Heat sink, LCD-TV, laptop, PC, telecom device, wireless hub, DDR II module, etc.

Technical characteristics

Features	TGF_062_AB	Unit	Tolerance	Test Method
Color	Blue	-	-	Colorimètre CIE 1976
Density	3.1	g/cm ³	+/- 5%	ASTM D792
Thickness		mm	-	ASTM D374
Hardness	50	shore 00	+/- 15%	ASTM D2240
Sizes	310*310	mm	-	-
Thermal conductivity	6.2	W/mK	+/- 10%	ASTM D5470 Modified
Weight loss	< 1	%	-	ASTM E595
Elongation	50	%	-	ASTM D412
Breakdown voltage	≥ 10	kV/mm	-	ASTM D149
Volume resistance	1×10 ¹³	Ohm-m	-	ASTM D257
UL certification	V-0	-	-	UL 94
Temperature	-50 to 180	°C	-	-

The TGF_062_AB is available in thicknesses from 0.5 to 11mm.



The results were obtained under laboratory conditions and should be considered only as an indication. As AB2E has no control over its customers' equipment and many other factors, it is the user's responsibility to carry out its own tests to ensure that the product corresponds to its needs.

